

**Amendments to the claims:****Claims 1-21 (canceled)**

**Claim 22 (previously presented): A slurry for polishing a barrier layer that serves to isolate a copper layer from a dielectric layer comprising a mixture of:**

about 14.7 grams per liter of a citric acid salt;

between about 4.4% and about 8.8% by volume of a silica based abrasive; and

about .38 grams per liter of a 30% H<sub>2</sub>O<sub>2</sub> solution.

**Claim 23 (previously presented): The slurry of claim 22 wherein the mixture includes about 8.8% by volume of a precipitated silica abrasive, has a pH that is about 7.4, and wherein the citric acid salt is potassium citrate.**

**Claims 24-26 (canceled)**